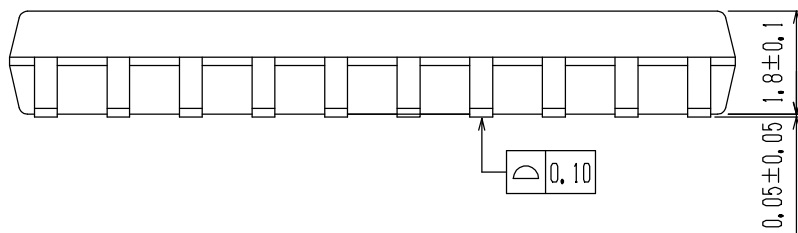
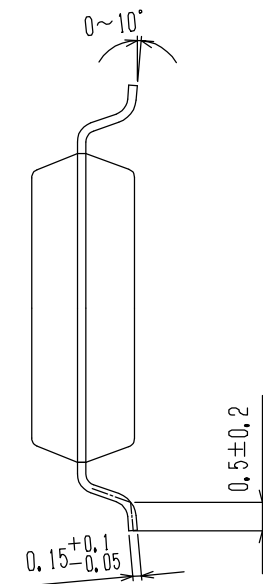
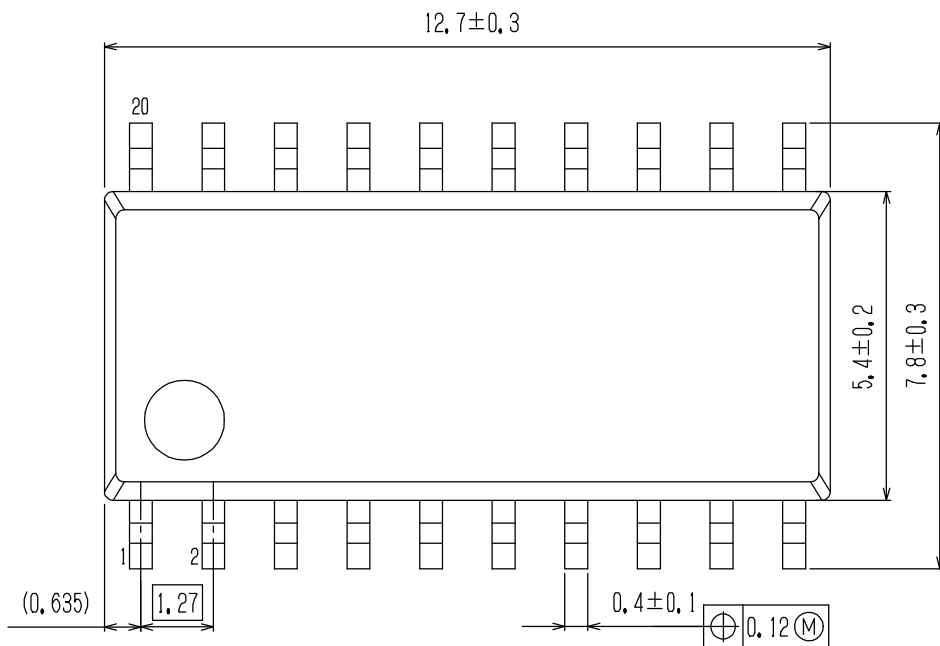
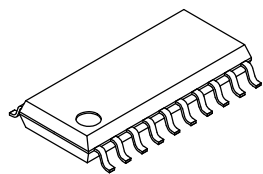


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC20W / MFP20J (300 mil)
CASE 751DE
ISSUE O

DATE 31 MAY 2012



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